E01C-2G4M01S1B User Manual

2.4GHz SoC Wireless Module



Chengdu Ebyte Electronic Technology Co.,Ltd.

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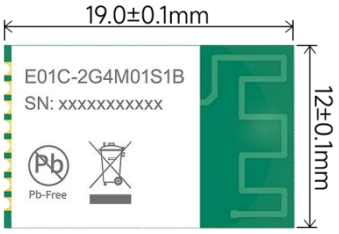
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1. Overview

1.1 Introduction

E01C-2G4M01S1B is a 2.4GHz SMD wireless module with PCB antenna developed by Ebyte. With industrial grade high precision 16MHz crystal, the RF performance and component selection of the module are in accordance with industrial standards. It has obtained FCC, CE, RoHS and other domestic and foreign authoritative certification.

E01C-2G4M01S1B is a pure RF transceiver module. MCU driver or special SPI debugging tool is required.



1.2 Features

- Ultra-small size: 12 * 19mm;
- Communication distance is up to 200m;
- The maximum transmit power is 5dBm (31mW), the software is adjustable for multiple levels;
- Global license-free ISM 2.4GHz band;
- Air data rate : 2Mbps, 1Mbps and 250kbps;
- 125 communication channels to meet the needs of multi-point communication, packet, frequency hopping and other applications;
- Connect to MCU through SPI interface, the speed is 0 ～ 10Mbps;
- 2.0V ~ 3.6V power supply, ≥3.3V power supply can ensure the best performance;
- Industrial-grade standard design, good for long-term use from -40 to 85 ° C;
- PCB antenna;
- Enhanced ShockBurst, fully compatible with all NORDIC nRF24L, nRF24E, nRF24U series.

1.3 Application

- Wearable devices;
- Smart home and industrial sensors;
- Security system, positioning system;
- Wireless remote control, drone;
- Wireless game remote control;
- Healthcare products;
- Wireless voice, wireless headphones;
- Automotive industry applications.

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2 Technical Parameters

2.1 Limit Parameter

Main parameter	Performance		Remarks
	Min	Min	
Voltage supply（V）	0	3.6	Voltage over 3.6V will cause permanent damage to module
Blocking power（dBm）	-	10	Chances of burn is slim when modules are used in short distance
Working temperature（℃）	-40	85	

2.2 Working parameters

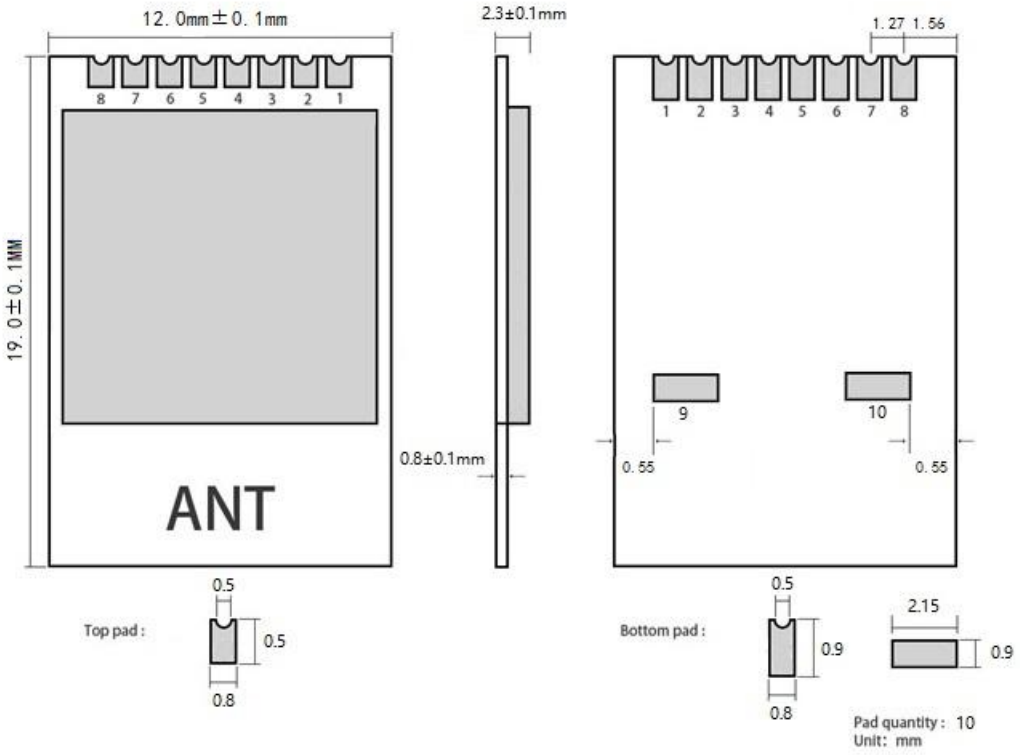
Main parameter		Performance			Remarks
		Min.	Typ.	Max.	
Operating voltage（V）		2.0	3.3	3.6	≥3.3 V ensures output power
Communication level（V）		--	3.3	--	For 5V TTL, it may be at risk of burning down
Working temperature（℃）		-40	25	85	Industrial design
Operating frequency（GHz）		2.4	--	2.525	Support ISM band
Power consumption	TX current（mA）	12.5	13	13.5	Instant power consumption
	RX current（mA）	11.5	12	12.5	
	Sleep current（μA）	--	0.7	--	Software is shut down
Max Tx power（dBm）		4.5	7	5.5	set as 0dBm via software, with PA
Receiving sensitivity（dBm）		-92	-83	-94	Air data rate is 250kbps
Air data rate（bps）		250k	250k	2M	Controlled by user's programming

Main parameter	Value	Remarks
Distance	200m	in open and clear air, at height of 2.5m，air data rate:250kbps
FIFO	32 Byte	Max packet length per time
Crystal Frequency	16MHz	--
Modulation	GFSK	--
Package	SMD	--
Connector	half hole 1.27mm	--
Communication interface	SPI	0-10Mbps
Size	12 * 19mm	with PCB antenna
Antenna	PCB	50 ohm impedance match

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3 Dimension and pin definition



Pin No.	Pin item	Pin direction	Application
1	VCC	Power supply	2.0 ~ 3.6V
2	CE	Input	Module control pin
3	CSN	Input	Chip select pin for starting new SPI communication
4	SCK	Input	SPI clock pin
5	MOSI	Input	SPI data input pin
6	MISO	Output	SPI data output pin
7	IRQ	Output	Interrupt request，valid in low level
8	GND		Ground, connected to power reference ground
9	GND		Ground, connected to power reference ground
10	GND		Ground, connected to power reference ground

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4 Basic operation

4.1 Hardware design

- It is recommended to use a DC stabilized power supply. The power supply ripple factor is as small as possible, and the module needs to be reliably grounded.;
- Please pay attention to the correct connection of the positive and negative poles of the power supply. Reverse connection may cause permanent damage to the module;
- Please check the power supply to ensure it is within the recommended voltage otherwise when it exceeds the maximum value the module will be permanently damaged;
- Please check the stability of the power supply, the voltage cannot be fluctuated frequently;
- When designing the power supply circuit for the module, it is often recommended to reserve more than 30% of the margin, so the whole machine is beneficial for long-term stable operation.;
- The module should be as far away as possible from the power supply, transformers, high-frequency wiring and other parts with large electromagnetic interference.;
- High-frequency digital routing, high-frequency analog routing, and power routing must be avoided under the module. If it is necessary to pass through the module, assume that the module is soldered to the Top Layer, and the copper is spread on the Top Layer of the module contact part(well grounded), it must be close to the digital part of the module and routed in the Bottom Layer;
- Assuming the module is soldered or placed over the Top Layer, it is wrong to randomly route over the Bottom Layer or other layers, which will affect the module's spurs and receiving sensitivity to varying degrees;
- It is assumed that there are devices with large electromagnetic interference around the module that will greatly affect the performance. It is recommended to keep them away from the module according to the strength of the interference. If necessary, appropriate isolation and shielding can be done;
- Assume that there are traces with large electromagnetic interference (high-frequency digital, high-frequency analog, power traces) around the module that will greatly affect the performance of the module. It is recommended to stay away from the module according to the strength of the interference. If necessary, appropriate isolation and shielding can be done.
- If the communication line uses a 5V level, a 1k-5.1k resistor must be connected in series (not recommended, there is still a risk of damage);
- Try to stay away from some physical layers such as TTL protocol at 2.4GHz , for example: USB3.0;

4.2 Software programming

- Insert the module on the user's circuit board, use the microcontroller to communicate with it through SPI or serial port, and operate its control register and transmit / receive buffer through the SPI instruction. Please refer to the latest nRF24L01P datasheet for the register read and write operations.

- IRQ is an interrupt pin. It is used to wake up the microcontroller and achieve fast response; users can leave it unconnected and use SPI to query the interrupt status (not recommended, not conducive to overall power consumption, low efficiency);

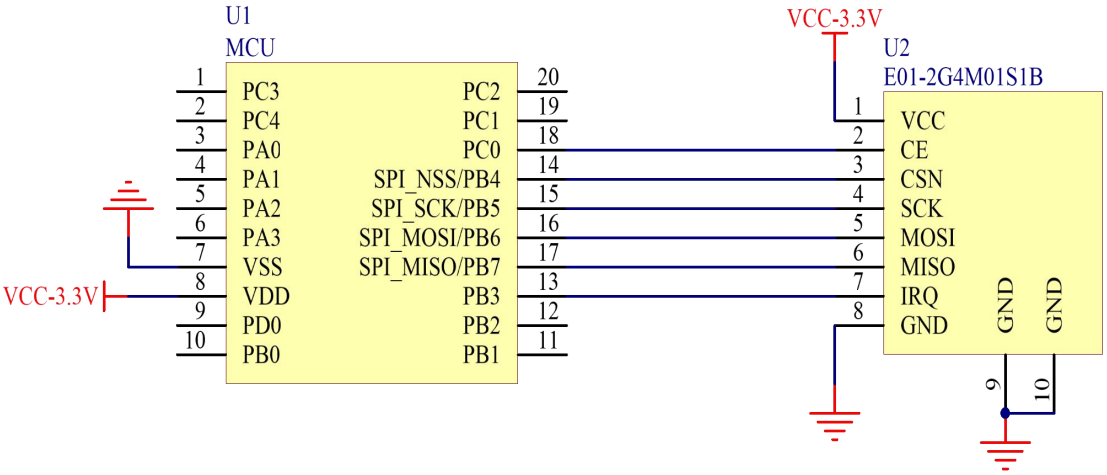
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- CE can be connected to high level for a long time, but the module must be set to POWER DOWN power-down mode when writing to the register. It is recommended that CE be controlled by MCU pin.

5 Basic application

5.1 Basic circuit diagram



6 FAQ

6.1 Communication range is too short

- The communication distance will be affected when obstacle exists.
- Data lose rate will be affected by temperature, humidity and co-channel interference.
- The ground will absorb and reflect wireless radio wave, so the performance will be poor when testing near ground.
- Sea water has great ability in absorbing wireless radio wave, so performance will be poor when testing near the sea.
- The signal will be affected when the antenna is near metal object or put in a metal case.
- Power register was set incorrectly, air data rate is set as too high (the higher the air data rate, the shorter the distance).
- The power supply low voltage under room temperature is lower than 2.5V, the lower the voltage, the lower the transmitting power.
- Due to antenna quality or poor matching between antenna and module.

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6.2 Module is easy to damage

- Please check the power supply to ensure that it is between the recommended power supply voltage. If the maximum value is exceeded, the module will be permanently damaged.
- Please check the stability of power source, the voltage cannot fluctuate too much.
- Please make sure anti-static measure are taken when installing and using, high frequency devices have electrostatic susceptibility.
- Please ensure the humidity is within limited range, some parts are sensitive to humidity.
- Please avoid using modules under too high or too low temperature.

6.3 BER(Bit Error Rate) is high

- There are co-channel signal interference nearby, please be away from interference sources or modify frequency and channel to avoid interference;
- Poor power supply may cause messy code. Make sure that the power supply is reliable.
- The extension line and feeder quality are poor or too long, so the bit error rate is high;

7 Soldering guidance

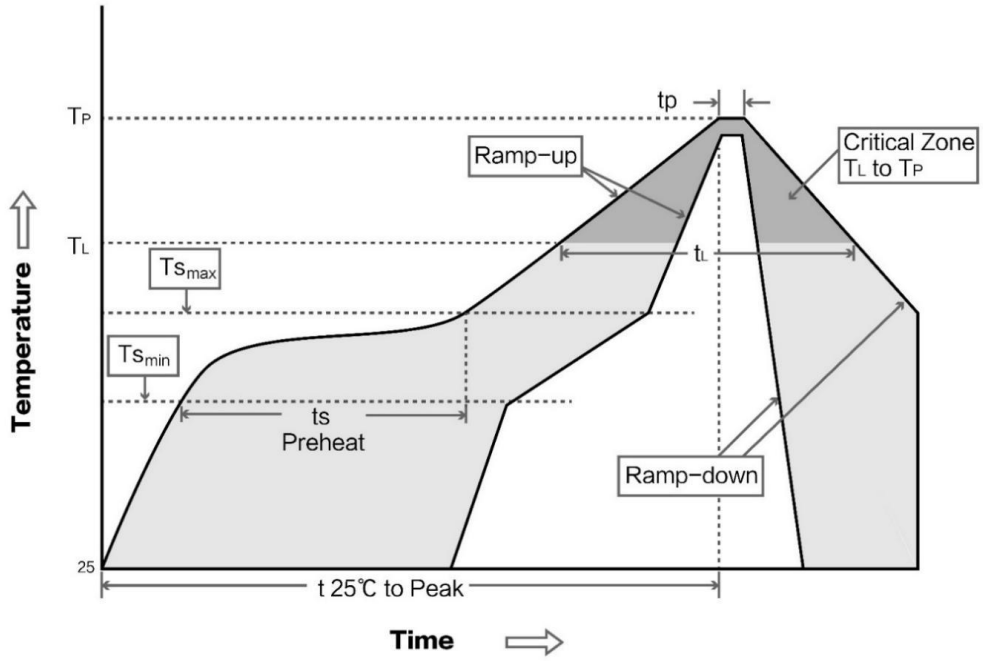
7.1 Reflow Soldering Temperature

Profile Feature	Curve feature	Sn-Pb Assembly	Pb-Free Assembly
Solder Paste	Solder paste	Sn63/Pb37	Sn96.5/Ag3/Cu0.5
Preheat Temperature min （Tsmin）	Minimum preheating temperature	100℃	150℃
Preheat temperature max (Tsmax)	Maximum preheating temperature	150℃	200℃
Preheat Time (Tsmin to Tsmax)(ts)	Preheating time	60-120 sec	60-120 sec
Average ramp-up rate(Tsmax to Tp)	Average rising rate	3℃/second max	3℃/second max
Liquidous Temperature (TL)	Liquid phase temperature	183℃	217℃
Time（tL）Maintained Above（TL）	Time above liquidus	60-90 sec	30-90 sec
Peak temperature（Tp）	Peak temperature	220-235℃	230-250℃
Aveage ramp-down rate（Tp to Tsmax）	Average descent rate	6℃/second max	6℃/second max
Time 25℃ to peak temperature	Time of 25 ° C to peak temperature	6 minutes max	8 minutes max

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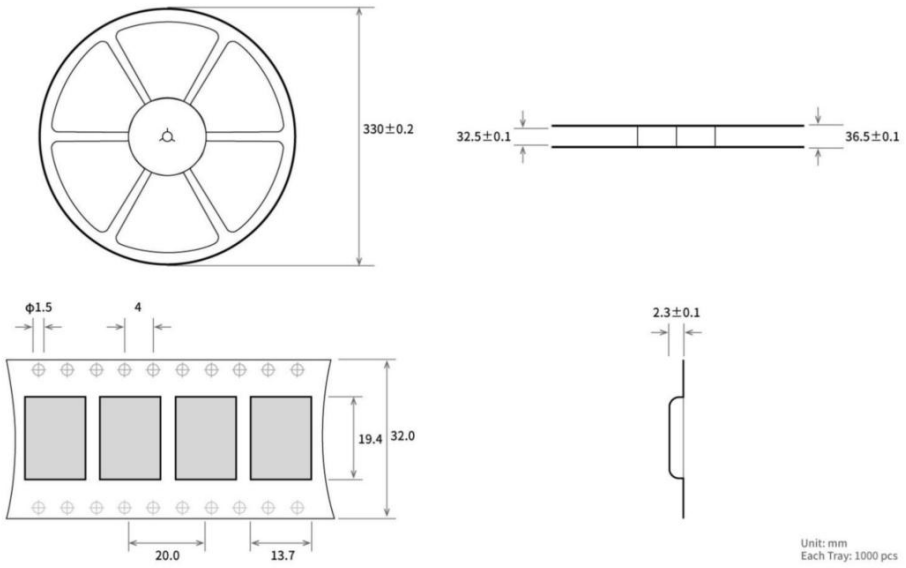
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7.2 Reflow Soldering Curve



8 Batch packaging

8.1 Tray



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Revision history

Version	Date	Description	Issued by
1.00	2024/9/30	Initial version	LAU

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